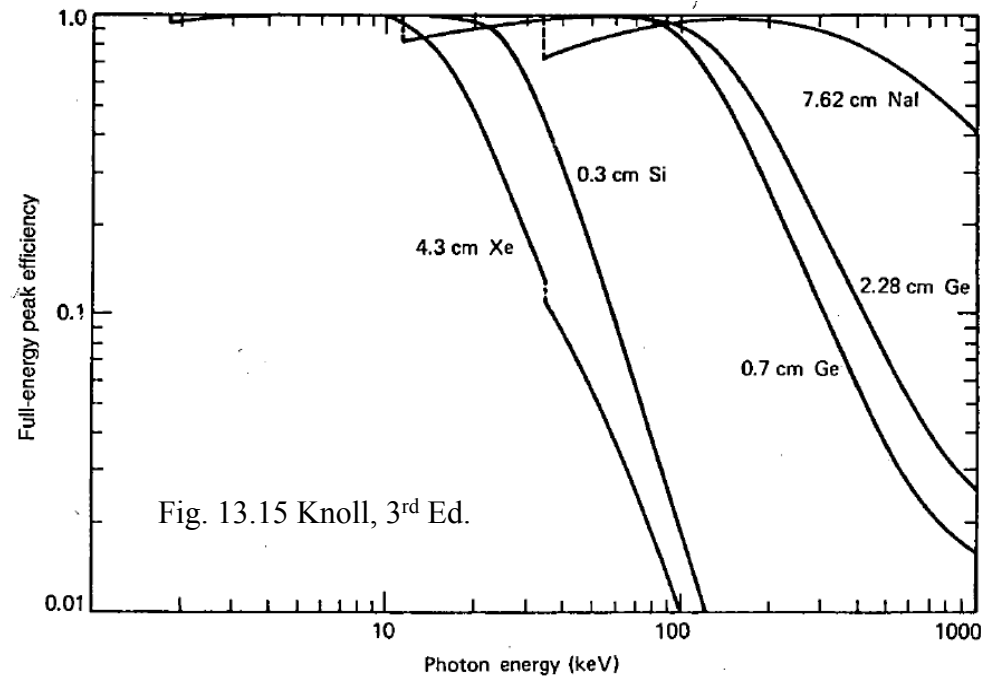


# Chap. 13 – Other Semiconductors



## Detector comparison, (thickness given)

NaI(Tl) has a significantly higher stopping power for ~ MeV gamma rays than Ge and especially Si – significant effort has been applied to finding other semiconducting materials with higher atomic numbers.

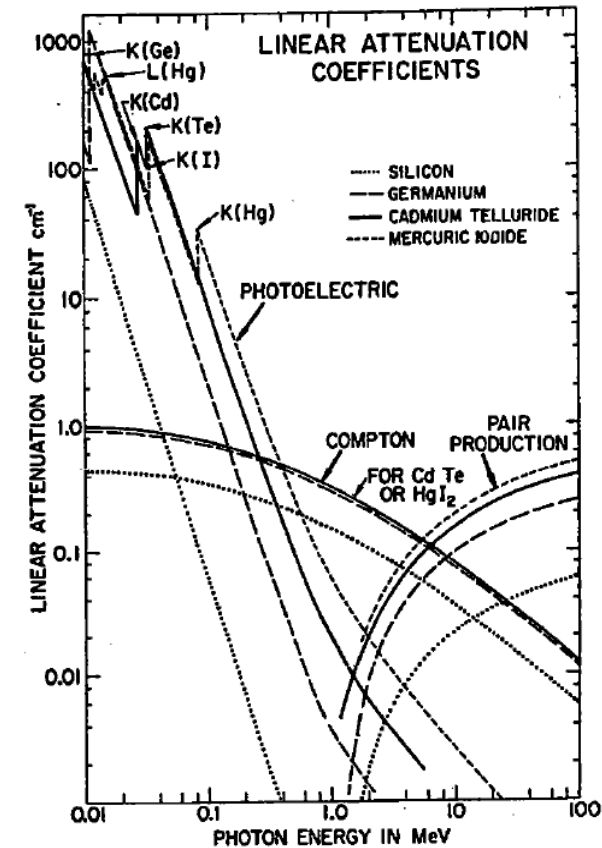


Fig. 13.22 Knoll, 3<sup>rd</sup> Ed.

# Other Semiconductor Properties

| Material                       | Z        | Bandgap [eV] | Mobility [cm <sup>2</sup> /Vs] |       | Density g/cm <sup>3</sup> |
|--------------------------------|----------|--------------|--------------------------------|-------|---------------------------|
|                                |          |              | electrons                      | holes |                           |
| Si                             | 14       | 1.1          | 1350                           | 480   | 2.3                       |
| Ge                             | 32       | 0.7          | 3800                           | 1800  | 5.3                       |
| Diamond                        | 6        | 5.5          | 1800                           | 1200  | 3.5                       |
| GaAs                           | 31-33    | 1.5          | 8600                           | 400   | 5.4                       |
| AlSb                           | 13-51    | 1.6          | 200                            | 700   | 4.3                       |
| GaSe                           | 31-34    | 2.0          | 60                             | 250   | 4.6                       |
| CdSe                           | 48-34    | 1.7          | 50                             | 50    |                           |
| CdS                            | 48-16    | 2.4          | 300                            | 15    | 4.8                       |
| InP                            | 49-15    | 1.4          | 4800                           | 150   |                           |
| ZnTe                           | 30-52    | 2.3          | 350                            | 110   |                           |
| WSe <sub>2</sub>               | 74-34    | 1.4          | 100                            | 80    |                           |
| BiI <sub>3</sub>               | 83-53    | 1.7          | 680                            | 20    |                           |
| Bi <sub>2</sub> S <sub>3</sub> | 83-16    | 1.3          | 1100                           | 200   | 6.7                       |
| Cs <sub>3</sub> Sb             | 55-51    | 1.6          | 500                            | 10    |                           |
| PbI <sub>2</sub>               | 82-53    | 2.6          | 8                              | 2     | 6.2                       |
| HgI <sub>2</sub>               | 89-53    | 2.1          | 100                            | 4     | 6.3                       |
| CdTe                           | 48-52    | 1.5          | 1100                           | 100   | 6.1                       |
| CdZnTe                         | 48-30-52 | 1.5-2.4      |                                |       |                           |

Recall correlation of W with band gap – higher W leads to lower signal but also lower thermal noise.

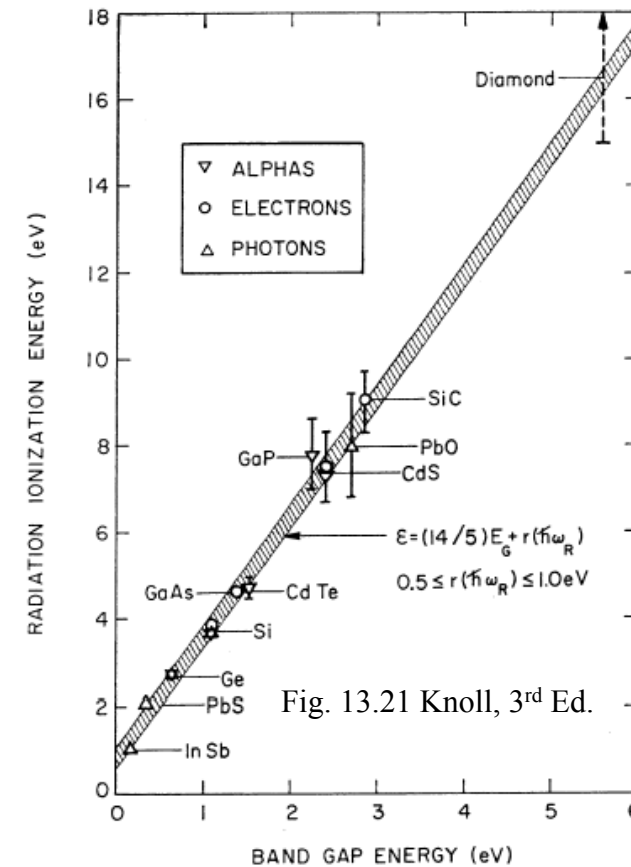
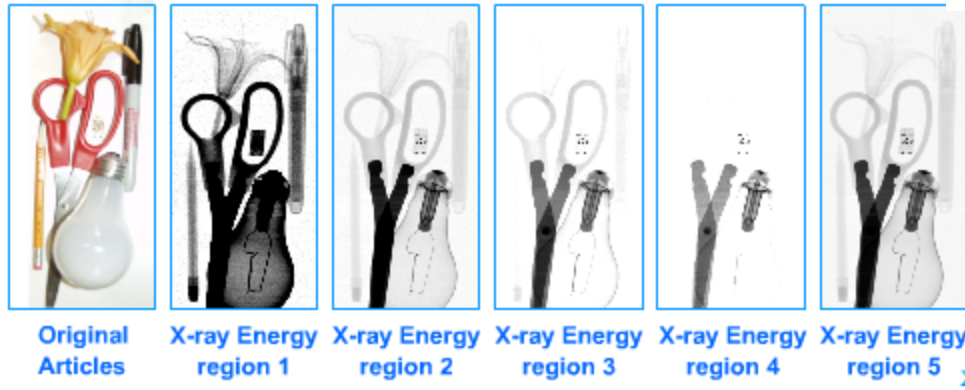
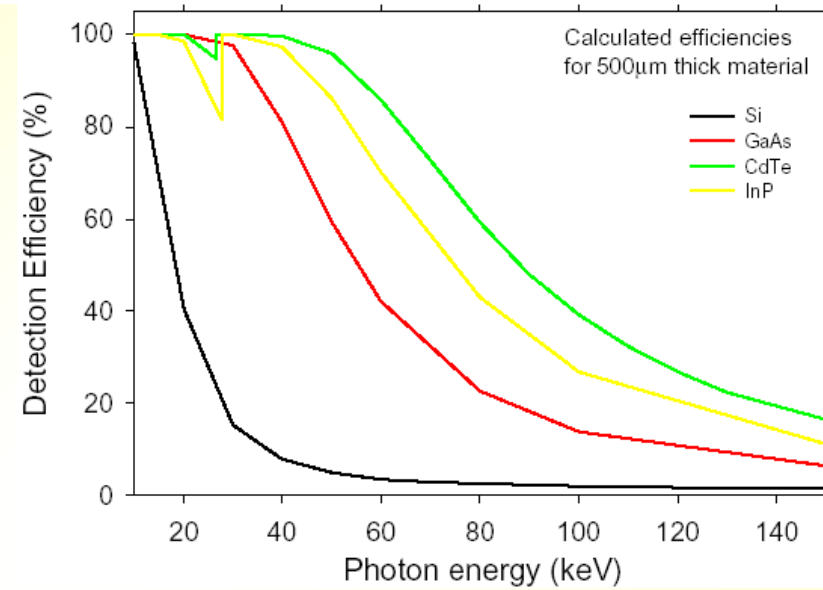
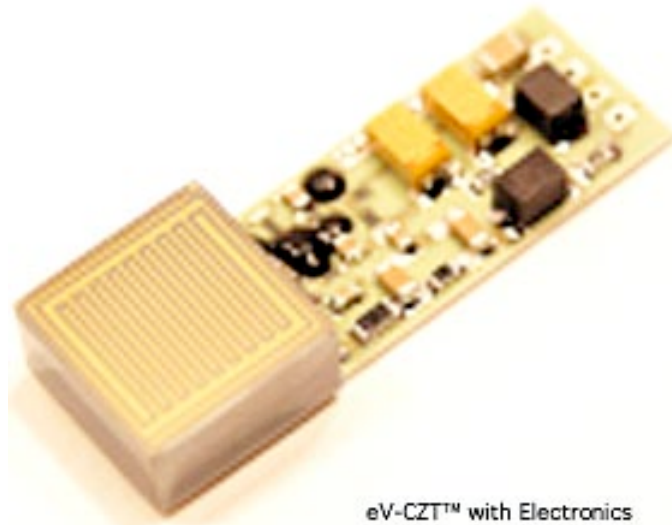


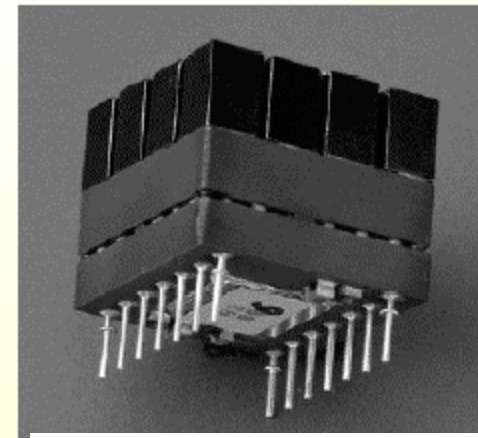
Fig. 13.21 Knoll, 3<sup>rd</sup> Ed.

# Other Semiconductors – CZT



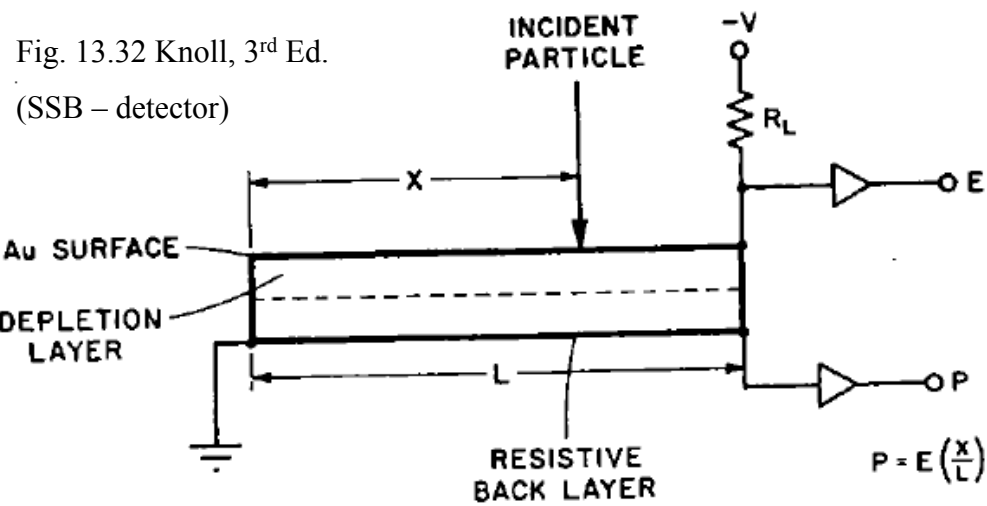
Typical sensitivity of integrated device: 0.1 mRem/hr to 1 Rem/hr

Imaging device, 4.5x4.5x6 mm<sup>3</sup> in 4x4 array from BICRON

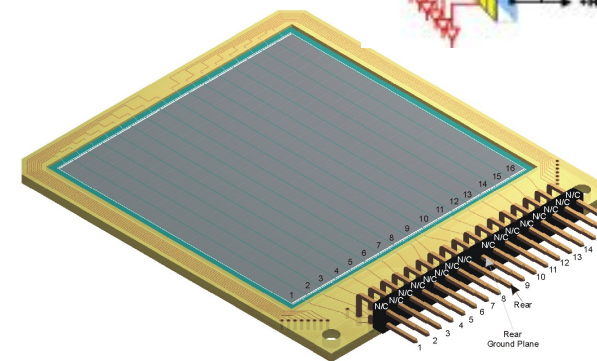
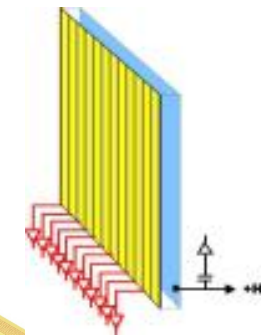
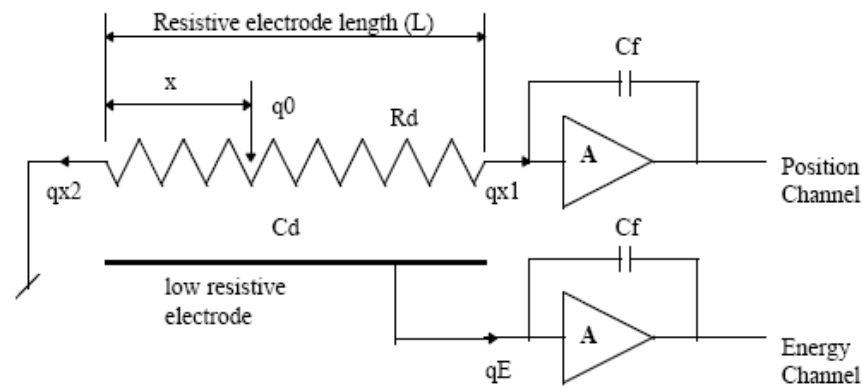


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# Position Sensitivity [Simple]

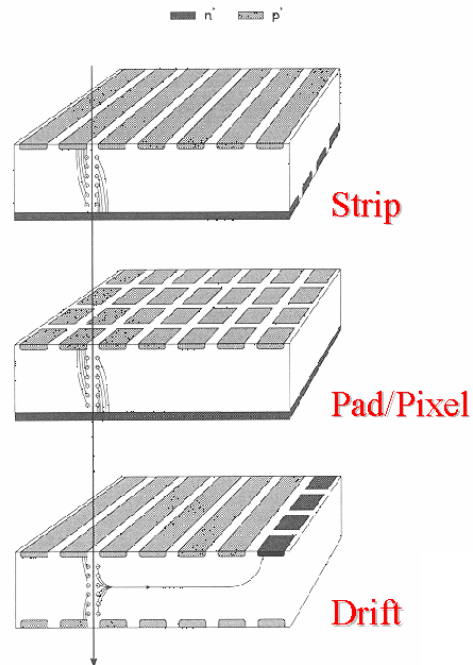
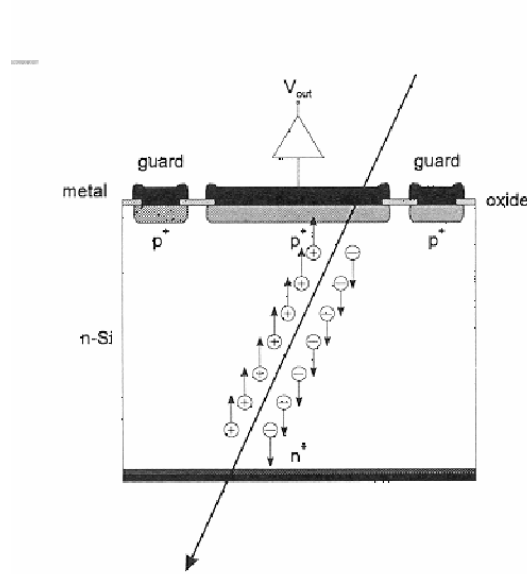


ORTEC PSD n-type, B-contact



Charge division:  
 $q_0 = q_{x1} + q_{x2} + qE$

# Position Sensitivity [Patterns]

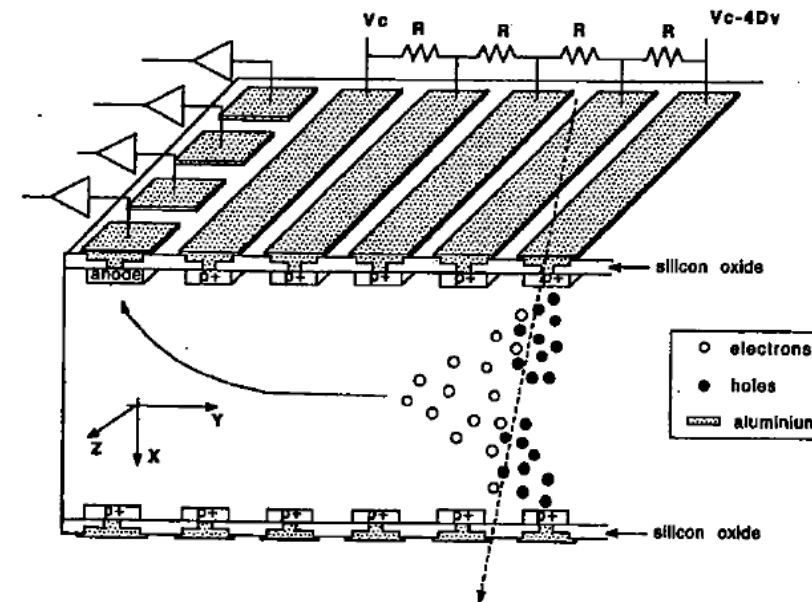


One readout channel / strip

One readout channel / pad

One readout channel / pad & Time

Drift detectors .. Continuous readout



# Position Sensitivity [CCD]

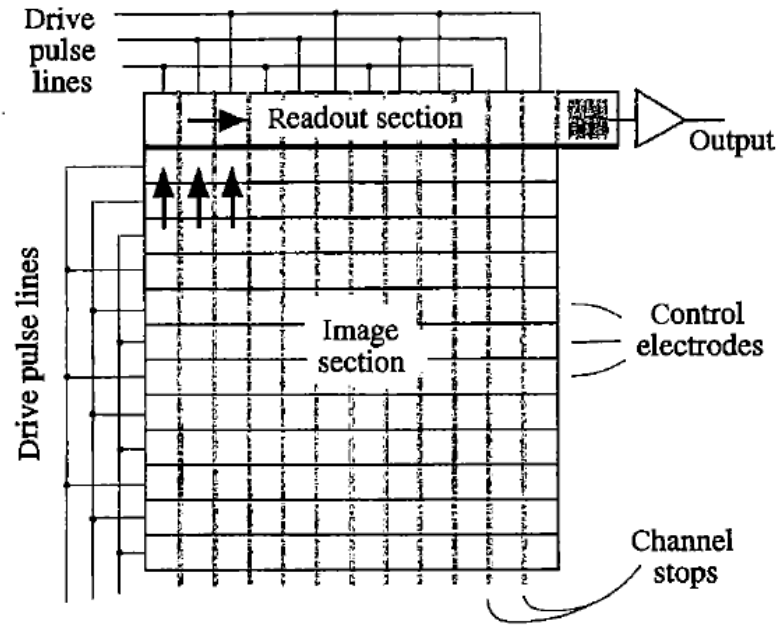


Fig. 13.38 Knoll, 3<sup>rd</sup> Ed.

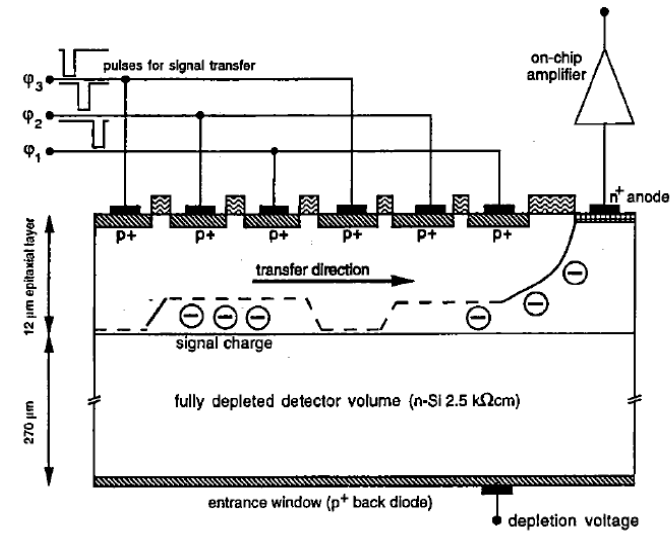


Fig. 13.39 Knoll, 3<sup>rd</sup> Ed.

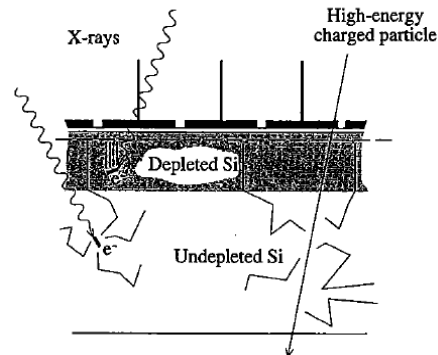


Fig. 13.40 Knoll, 3<sup>rd</sup> Ed.

## Chap. 13 – CCD Readout Question

Problem 13.8 – A fully depleted silicon CCD is 300  $\mu\text{m}$  thick and used to form a recorded image of incident x-rays whose energy is 10 keV. It has an array of 256 x 256 pixels per frame and is operated in a simple mode of alternating exposure and readout. The readout frequency is 100 kHz. The exposure time per frame is to be kept at least 20 times the total readout time. The same measurement is designed to measure the energy deposited by each individual x-ray so that probability of multiple hits should be less than 5% per pixel during exposure.

- a) Determine the maximum x-ray interaction rate in the full image.
- b) Find the minimum required storage capacity for electrons in one pixel.
- c) If the charge due to leakage is to be kept less than 10% of the signal charge due to a single x-ray interaction in a pixel, estimate the maximum leakage current for the entire device.